

# S720

## Product Specifications

Issue 1.1



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This document provides a guide for users to use S720.

This document is intended for system engineers (SEs), development engineers, and test engineers.

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# About This Document

## Scope

This document is applicable to the S720 module. It describes the S720 basic information, key indicators, appearance, dimensions, assembly, packaging, storage, and other information.




## Audience

This document is intended for system engineers (SEs), development engineers, and test engineers.

## Change History

| Issue | Change  | Author        |
|-------|---|---------------|
| 1.0   | Initial issue.  | Yin Xiaoliang |
| 1.1   | <ul style="list-style-type: none"> <li>Added the EA variant and frequency bands.</li> <li>Updated the operating bands, TX power, and RX sensitivity.</li> <li>Changed the typical value of VBAT to 3.6 V.</li> <li>Updated the pin layout and the caution in electrical characteristics.</li> </ul> | Yin Xiaoliang |

## Conventions

| Symbol  | Description  |
|---|--|
|  | Indicates danger or warning. This information must be followed. Otherwise, a catastrophic module or user device failure or bodily injury may occur.              |
|  | Indicates caution. This symbol alerts the user to important points about using the module. If these points are not followed, the module or user device may fail. |
|  | Indicates instructions or tips. This symbol provides advices or suggestions that may be useful when using the module.  |

## Related Documents

Neoway\_S720\_Datasheet

Neoway\_S720\_Hardware\_User\_Guide

Neoway\_S720\_EVK\_User\_Guide

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# 1 Safety Recommendations

Ensure that this product is used in compliance with the requirements of the country and environment. Read the following safety recommendations to avoid bodily injuries or damages of the product or workplace:

- Do not use this product at any places with a risk of fire or explosion.

If this product is used in a place with flammable gas or dust, such as propane gas, gasoline, and flammable spray, it will cause an explosion or a fire.

- Disable the wireless communication function in places where wireless communication is prohibited.

Do not use this product that can interfere with other electronic devices in environments, such as hospitals and airplanes.

Follow the requirements below during the application design and use of this product:

- Do not disassemble this product without permission from Neoway. Otherwise, we are entitled to refuse to provide further warranty.
- Design your application correctly based on the hardware user guide. Connect this product to a stable power supply and route traces following fire safety standards.
- Avoid touching the pins of this product to prevent damages caused by ESD.
- Do not insert or remove a USIM card or mobile memory card if it is not powered off.

## 2 About S720

S720 is an LTE smart module based on the UNISOC quad-core SOC platform. It supports FDD-LTE, TDD-LTE, WCDMA, and GSM network modes, and supports GNSS, Bluetooth4.2, and Wi-Fi2.4G. It supports display, camera, SD, MIC, speaker, headset, USB2.0, and more.

### 2.1 Product Overview

Table 2-1 lists the variant and frequency bands supported by the S720 module.

Table 2-1 Variants and frequency bands supported

| Variant | Region | Category | Frequency Band   | GNSS      | Wi-Fi     | BT        |
|---------|--------|----------|--|-----------|-----------|-----------|
| S720-CA | China  | Cat4     | LTE-FDD: B1/B3/B5/B8<br>LTE-TDD:<br>B34/B38/B39/B40/B41<br>WCDMA: B1/B5/B8<br>GSM:900/1800 MHz         | Supported | Supported | Supported |
| S720-EA | Europe | Cat4     | LTE-FDD:<br>B1/B3/B5/B7/B8/B20/B28<br>LTE-TDD: B38/B40/B41<br>WCDMA: B1/B5/B8<br>GSM: 850/900/1800 MHz | Supported | Supported | Supported |

The S720 module has 274 pins and uses the 146-pin LCC+128-pin LGA package. Its dimensions are (40.50±0.1) mm × (40.50±0.1) mm × (2.85±0.2) mm. This module supports running of the Android10 system. It is suitable for smart POS, smart gateway, video surveillance, event data recorder, DVR, in-vehicle payment equipment, law enforcement equipment, smart handheld equipment, smart wearable, vending machine, logistics cabinet, and other terminals. It can meet the needs of users for high rate and multimedia functions in industrial, in-vehicle, and consumer applications.

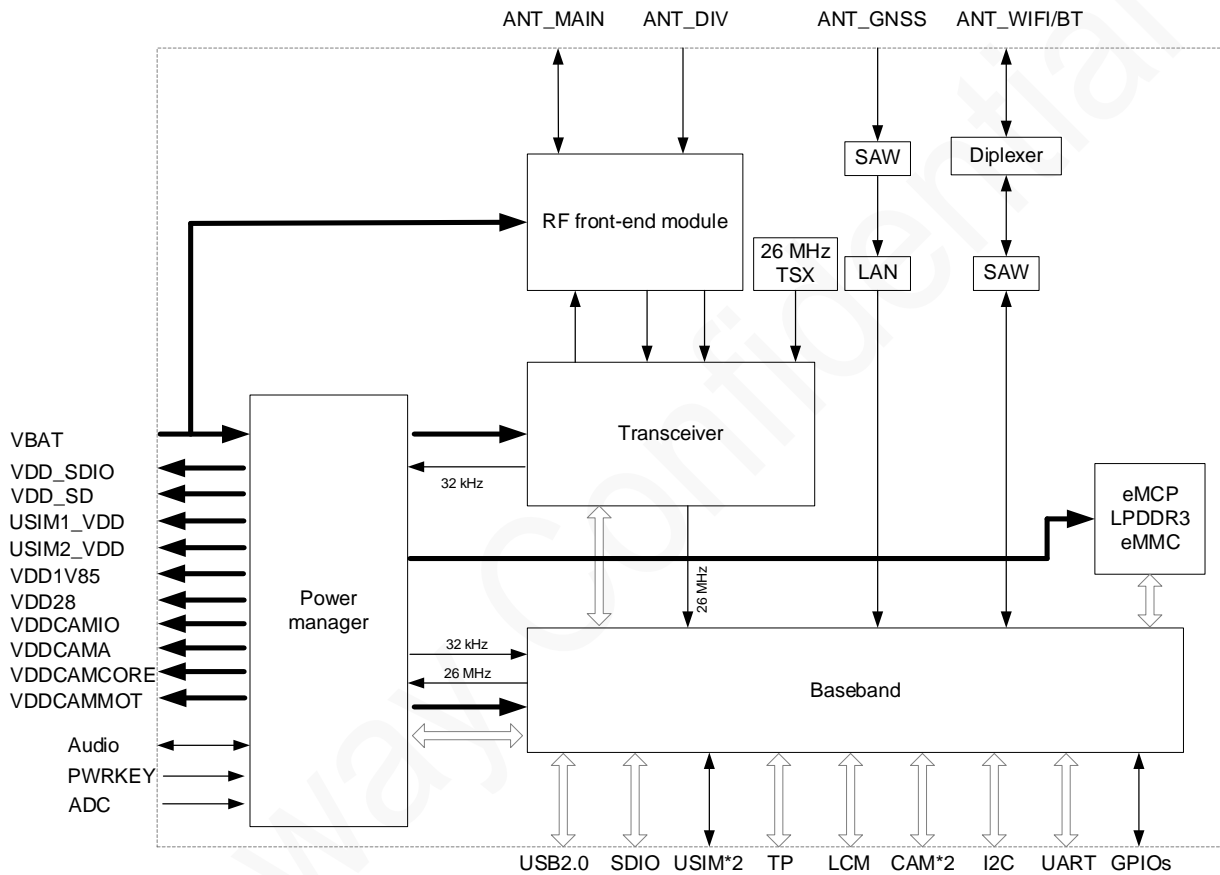
### 2.2 Block Diagram

S720 consists of the following functional units:

- Baseband

- Crystal
- Power manager
- LPDDR3+eMMC memory
- Digital interfaces (USB/USIM/UART/I2C/camera/SDIO3.0/LCD/TP)
- Analog interfaces (audio/ADC)
- RF part (2G/3G/4G antenna, GNSS antenna, 2.4G Wi-Fi&Bluetooth antenna)

Figure 2-1 Block diagram



## 2.3 Basic Features

Table 2-2 Basic features of the S720 module

| Parameter         | Description   |
|-------------------|---|
| Physical features | <ul style="list-style-type: none"> <li>• Dimensions: (40.50±0.1) mm × (40.50±0.1) mm × (2.85±0.2) mm</li> <li>• Weight: about 10.4 g</li> <li>• Package: 146-pin LCC+128-pin LGA</li> </ul> |
| Temperature range | <p>Operating temperature range: -30°C to +75°C</p> <p>Storage temperature range: -40°C to +90°C</p>   |

|                           |  |
|---------------------------|--|
| Operating voltage (DC)    | VBAT: 3.5 V to 4.2 V, typical value: 3.6 V   |
| Operating current (DC)    | Sleep mode <sup>1)</sup> : TBD   |
|                           | Idle mode <sup>2)</sup> : TBD  |
| Certification approval    | CCC*, SRRC*  |
| <b>Platform features</b>  |  |
| Application processor     | Quad-core 64-bit ARM Cortex-A53 processor, main frequency up to 1.4 GHz.   |
| GPU                       | Mali-T820 MP1 GPU, frequency up to 680 MHz.  |
| Operating system          | Android 10   |
| Memory                    | 1 GB LPDDR3+8 GB eMMC (default)<br>2 GB LPDDR3+16 GB eMMC (optional)   |
| <b>RF features</b>        |  |
| Wireless rate             | GPRS: Max 107 kbps (DL)/Max 85.6 kbps (UL)<br>EDGE: Max 296 kbps (DL)/Max 236.8 kbps (UL)<br>WCDMA: HSDPA, Max 42 Mbps (DL)/Max 11.2 Mbps (UL)<br>FDD-LTE: Cat4, Max 150 Mbps (DL)/Max 50 Mbps (UL)<br>TDD-LTE: Cat4, Max 130 Mbps (DL)/Max 35 Mbps (UL)   |
| Power class               | EGSM900: 33 dBm+1/-3 dB (Power Class 4)<br>DCS1800: 30 dBm+1/-3 dB (Power Class 1)<br>EDGE 900 MHz: 27 dBm±3 dB (Power Class E2)<br>EDGE 1800 MHz: 26 dBm±3 dB (Power Class E2)<br>WCDMA: 24 dBm+1/-3 dB (Power Class 3)<br>FDD-LTE: 23 dBm+1/-3 dB (Power Class 3)<br>TDD-LTE: 23 dBm+1/-3 dB (Power Class 3) |
| Satellite positioning     | GPS/BDS/GLONASS  |
| Antenna interface         | 2G/3G/4G antenna, 4G diversity reception antenna, GNSS antenna, 2.4G Wi-Fi/BT antenna. The characteristic impedance of each antenna is 50 Ω.   |
| <b>Multimedia</b>         |  |
| Display interface         | Support for one 4-lane MIPI_DSI with a maximum rate of 1.5 Gbps/lane. The highest resolution supports HD+(1440x720)@60fps.   |
| Camera interface          | Two MIPI_CSI, with a maximum rate of 1.5 Gbps/lane. The rear-facing camera uses 2-lane MIPI and supports up to 8 MP. The front-facing camera uses 1-lane MIPI and supports up to 2 MP.   |
| Video coding and decoding | Coding: H.264/H.263/MPEG4 - 1080p@30fps<br>Decoding: H.264/H.263/MPEG4/VP8 - 1080p@30fps   |
| Graphics engine           | Mali-T820 MP1 GPU, up to 680 MHz 3D high-performance graphics engine.  |
| <b>Audio</b>              |  |
| Audio format              | GSM-FR, GSM-EFR, GSM-HR, AMR, AMR-NB, AMR-WB, EVS-NB, EVS-WB, EVS-SWB, MP3, AAC, AAC+, PCM.  |

|                                |  |
|--------------------------------|--|
| Audio input                    | Three MICs: one main MIC, one auxiliary MIC, one headset MIC.  |
| Audio output                   | Class AB stereo headset output.<br>Class AB differential earpiece output.<br>Class D differential speaker power amplifier output.  |
| <b>Connectivity features</b>   |  |
| UART                           | One 4-wire UART interface, support for hardware flow control.<br>Two 2-wire UART interfaces, of which the debug UART interface is only used for debugging.<br>Rate up to 2 Mbps. |
| I2C                            | Four I2C interfaces, used for peripherals such as cameras, touch screens, and sensors.   |
| USIM                           | Two (U)SIM card interfaces.<br>Support for (U)SIM cards: 1.8 V and 3.0 V.<br>Support for dual SIM dual standby.  |
| USB                            | One USB2.0 high-speed interface.<br>Support for USB2.0 high speed mode and USB OTG, used for data transfer, software commissioning, and software upgrade.                        |
| SDIO                           | One SDIO interface, support for the SD3.0 protocol, and support for 1.8 V or 3.0 V SD cards.   |
| ADC                            | One ADC interface, support for up to 12-bit sampling precision. Voltage detection range: 0 V to 1.2 V.   |
| WLAN                           | Support for the AP mode and STA mode.<br>2.4 GHz band: support for 802.11b/g/n, with a maximum rate of 72.2 Mbps.  |
| Bluetooth                      | BT4.2 or earlier.  |
| <b>Commissioning interface</b> |  |
| Forced download mode           | Forced USB boot control.   |

\* indicates in development.



Sleep mode<sup>1)</sup>: indicates that the module enters the airplane mode, and all radio frequency functions are disabled.

Idle mode<sup>2)</sup>: indicates that the module enters the low power consumption state. In this state, the peripheral interface of the module is disabled, but radio frequency functions are normal. The module will exit the idle mode when there is an incoming call or an SMS message, and will re-enter the idle mode when the incoming call and voice end.

## 3 Reference Standards

The S720 module design references the following standards:

- 3GPP TS 36.521-1 V10.0.0 User Equipment (UE) conformance specification; Radio transmission and reception;
- 3GPP TS 21.111 V9.0.0 USIM and IC card requirements
- 3GPP TS 31.102 V9.19.0 Characteristics of the Universal Subscriber Identity Module (USIM) application
- 3GPP TS 31.111 V9.12.2 Universal Subscriber Identity Module (USIM) Application Toolkit (USAT)

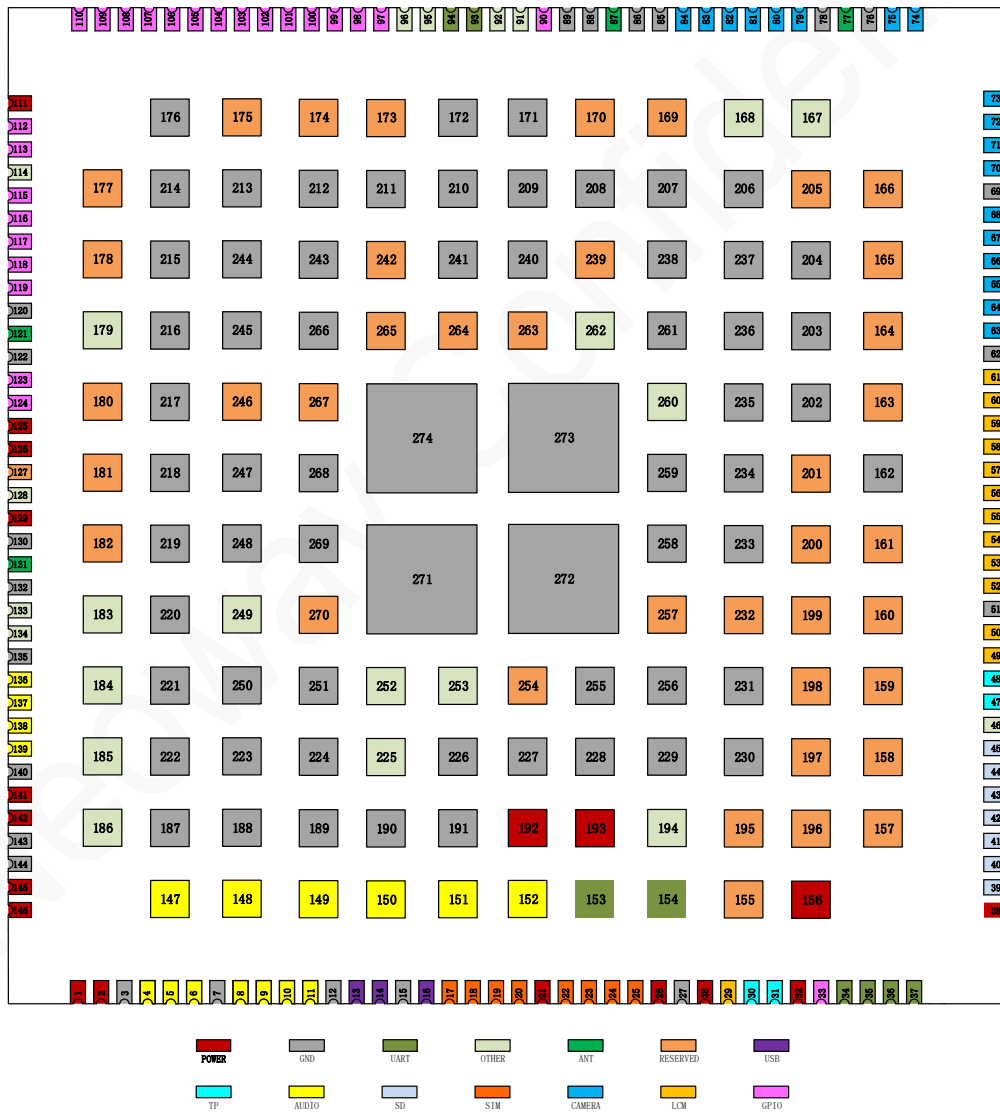
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# 4 Module Pins

The S720 module has 274 pins and uses the 146-pin LCC+128-pin LGA package.

## 4.1 Pin Layout

Figure 4-1 Pin layout of the S720 module

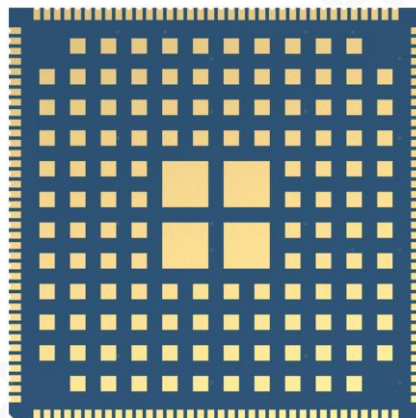


## 4.2 Module Appearance

Figure 4-2 Top view of the S720 module



Figure 4-3 Bottom view of the S720 module



These are renderings of the S720 module. For the actual appearance, see the module that you receive from Neoway.

## 5 Electrical Characteristics and Reliability

This chapter describes the electrical characteristics and reliability of the S720 module, including the input voltage and current of the power supply, the operating and storage temperature ranges, and the ESD protection characteristics.

### 5.1 Electrical Characteristics



- If the voltage is excessively low, the module might fail to start. If the voltage is excessively high or there is an instantaneous voltage burst during the startup, the module might be damaged permanently.
- If you use LDO or DC-DC to supply power to the module, ensure that the output current is at least 3 A. The 3 A current occurs when the module is working at the maximum power level of the GSM mode. The peak current during burst transmission has a short duration. Placing a large capacitor on the VBAT pin of the module can effectively enhance the freewheeling capability of the power supply and prevent excessive voltage drops that cause exceptions, such as module shutdown.

Table 5-1 Electrical characteristics of the S720 module

| Parameter |          | Minimum Value | Typical Value | Maximum Value |
|-----------|----------|---------------|---------------|---------------|
| VBAT      | $V_{in}$ | 3.5 V         | 3.6 V         | 4.2 V         |
|           | $I_{in}$ | -             | -             | 3 A           |
| USB_VBUS  | $V_{in}$ | 4.5 V         | 5.0 V         | 9.2 V         |

### 5.2 Temperature Characteristics



If the ambient temperature is not in the operating temperature range of the module, certain RF performance indicators of the module may deteriorate.

Figure 5-1 Temperature characteristics of the S720 module

| Parameter             | Minimum Value | Typical Value | Maximum Value |
|-----------------------|---------------|---------------|---------------|
| Operating temperature | -30°C         | 25°C          | 75°C          |
| Storage temperature   | -40°C         | 25°C          | 90°C          |

## 5.3 ESD Protection Characteristics

Electronic products need to pass ESD tests. The following table shows the ESD capability of key pins of the module. It is recommended to add ESD protection based on the application industry of the product to ensure product quality when designing a product.

Test environment: humidity 45%; temperature 25°C

Table 5-2 ESD protection characteristics

| Test Point      | Contact Discharge | Air Discharge |
|-----------------|-------------------|---------------|
| GND             | TBD               | TBD           |
| ANT             | TBD               | TBD           |
| Shielding cover | TBD               | TBD           |
| Others          | TBD               | TBD           |

## 6 RF Characteristics

The S720 module supports 2G/3G/4G network modes and frequency bands, as well as GNSS positioning and Wi-Fi&BT connectivity. This chapter describes the RF characteristics, such as the operating bands, TX power, RX sensitivity, and GNSS parameters of the S720 module.

### 6.1 Operating Bands

Table 6-1 Operating bands of the S720 module

| Operating Band | Uplink        | Downlink      |
|----------------|---------------|---------------|
| GSM850         | 824–849 MHz   | 869–894 MHz   |
| EGSM900        | 880–915 MHz   | 925–960 MHz   |
| DCS1800        | 1710–1785 MHz | 1805–1880 MHz |
| WCDMA B1       | 1920–1980 MHz | 2110–2170 MHz |
| WCDMA B5       | 824–849 MHz   | 869–894 MHz   |
| WCDMA B8       | 880–915 MHz   | 925–960 MHz   |
| FDD-LTE B1     | 1920–1980 MHz | 2110–2170 MHz |
| FDD-LTE B3     | 1710–1785 MHz | 1805–1880 MHz |
| FDD-LTE B5     | 824–849 MHz   | 869–894 MHz   |
| FDD-LTE B7     | 2500–2570 MHz | 2620–2690 MHz |
| FDD-LTE B8     | 880–915 MHz   | 925–960 MHz   |
| FDD-LTE B20    | 791–821 MHz   | 832–862 MHz   |
| FDD-LTE B28    | 703–748 MHz   | 758–803 MHz   |
| TDD-LTE B34    | 2010–2025 MHz | 2010–2025 MHz |
| TDD-LTE B38    | 2570–2620 MHz | 2570–2620 MHz |
| TDD-LTE B39    | 1880–1920 MHz | 1880–1920 MHz |
| TDD-LTE B40    | 2300–2400 MHz | 2300–2400 MHz |
| TDD-LTE B41    | 2535–2655 MHz | 2535–2655 MHz |

## 6.2 TX Power and RX Sensitivity

Table 6-2 S720 TX power and RX sensitivity

| Band                 | Conducted TX Power | Conducted RX Sensitivity |
|----------------------|--------------------|--------------------------|
| GSM850               | 33 dBm+1/-3 dB     | < -108 dBm               |
| EGSM900              | 33 dBm+1/-3 dB     | < -108 dBm               |
| DCS1800              | 30 dBm+1/-3 dB     | < -107 dBm               |
| WCDMA B1             | 24 dBm+1/-3 dB     | < -109 dBm               |
| WCDMA B5             | 24 dBm+1/-3 dB     | < -109 dBm               |
| WCDMA B8             | 24 dBm+1/-3 dB     | < -109 dBm               |
| FDD-LTE B1 (10 MHz)  | 23 dBm+1/-3 dB     | < -98 dBm                |
| FDD-LTE B3 (10 MHz)  | 23 dBm+1/-3 dB     | < -98 dBm                |
| FDD-LTE B5 (10 MHz)  | 23 dBm+1/-3 dB     | < -98 dBm                |
| FDD-LTE B7 (10 MHz)  | 23 dBm+1/-3 dB     | < -97 dBm                |
| FDD-LTE B8 (10 MHz)  | 23 dBm+1/-3 dB     | < -98 dBm                |
| FDD-LTE B20 (10 MHz) | 23 dBm+1/-3 dB     | < -98 dBm                |
| FDD-LTE B28 (10 MHz) | 23 dBm+1/-3 dB     | < -98 dBm                |
| TDD-LTE B34 (10 MHz) | 23 dBm+1/-3 dB     | < -98 dBm                |
| TDD-LTE B38 (10 MHz) | 23 dBm+1/-3 dB     | < -97 dBm                |
| TDD-LTE B39 (10 MHz) | 23 dBm+1/-3 dB     | < -99 dBm                |
| TDD-LTE B40 (10 MHz) | 23 dBm+1/-3 dB     | < -98 dBm                |
| TDD-LTE B41 (10 MHz) | 23 dBm+1/-3 dB     | < -97 dBm                |



All values above were obtained in labs. The LTE frequency band indicators are tested under the conditions of 10 MHz bandwidth. In actual use, there will be some deviations under different network environments.

TDD-LTE B41 band frequency is 120 MHz, with the channel range of 40040-41240.

## 6.3 GNSS Parameters

Table 6-3 GNSS parameters

| Parameter                  | Description       |
|----------------------------|-------------------|
| GPS L1 operating frequency | 1575.42±1.023 MHz |

|  |                   |
|--|-------------------|
| GLONASS operating frequency                    | 1598.5–1606.5 MHz |
| BDS operating frequency                        | 1559.1–1563.1 MHz |
| Tracking sensitivity                           | TBD               |
| Acquisition sensitivity                        | TBD               |
| Positioning precision (in an open environment) | TBD               |
| Hot start time (in an open environment)        | < TBD             |
| Cold start time (in an open environment)       | < TBD (@-130 dBm) |
| Noise coefficient (CNRin/CNRout)               | TBD (@-130 dBm)   |
| GNSS antenna type                              | Passive antenna   |

## 6.4 WLAN/BT Characteristics

Table 6-4 WLAN/BT TX power and RX sensitivity

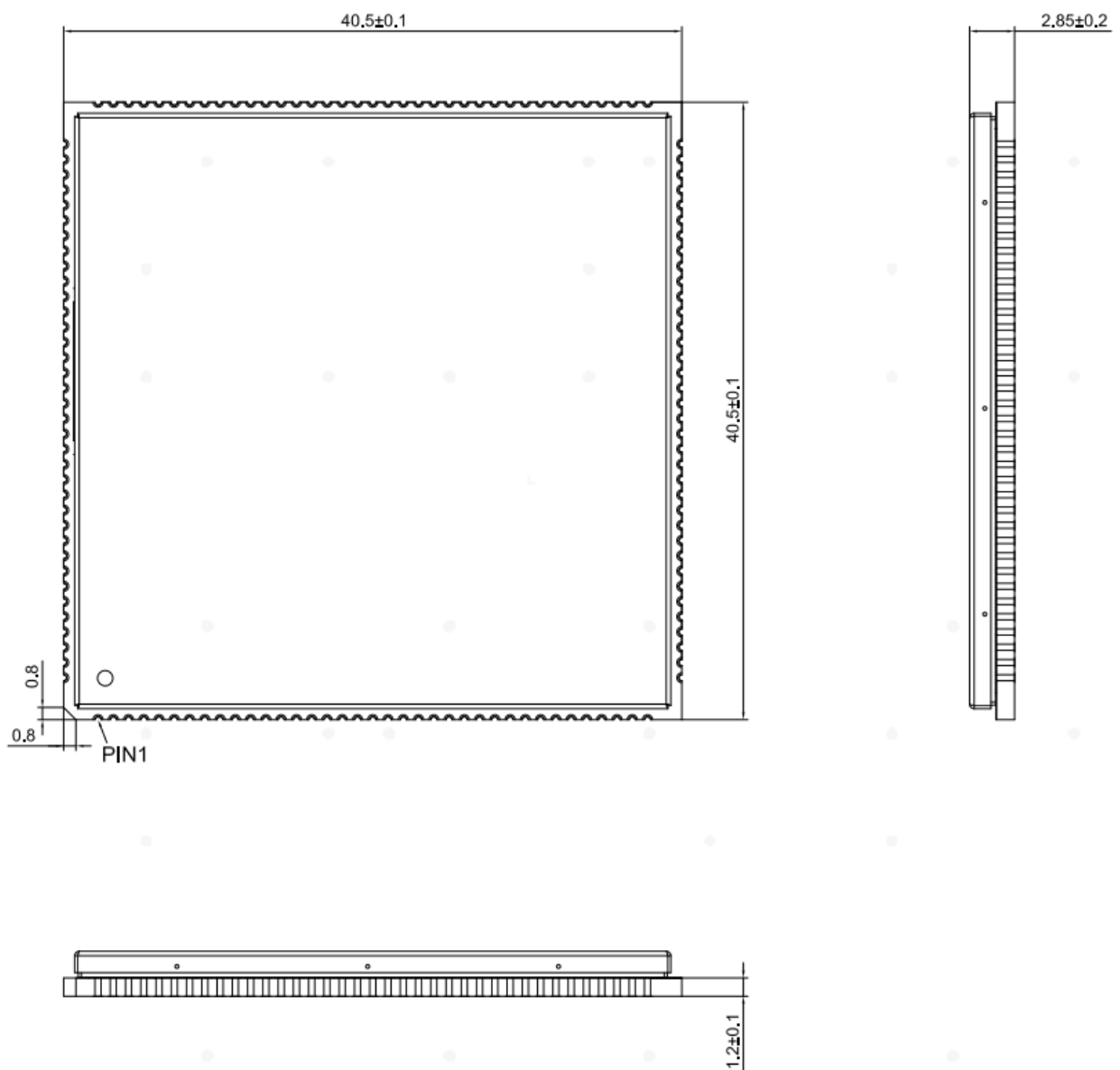
| Operating Band            | Rate    | TX Power | RX Sensitivity |
|---------------------------|---------|----------|----------------|
| 802.11b (2.4 GHz)         | 1 Mbps  | TBD      | TBD            |
|                           | 11 Mbps | TBD      | TBD            |
| 802.11g (2.4 GHz)         | 6 Mbps  | TBD      | TBD            |
|                           | 54 Mbps | TBD      | TBD            |
| 802.11n (2.4 GHz, 20 MHz) | MCS0    | TBD      | TBD            |
|                           | MCS7    | TBD      | TBD            |
| 802.11n (2.4 GHz, 40 MHz) | MCS0    | TBD      | TBD            |
|                           | MCS7    | TBD      | TBD            |
| Bluetooth                 | 1 Mbps  | TBD      | TBD            |

# 7 Mechanical Characteristics

This chapter describes the mechanical characteristics of the S720 module.

## 7.1 Dimensions

Figure 7-1 S720 top and side dimensions (unit: mm)



## 7.2 Label

The label uses laser engraving and can withstand a high temperature up to 260°C.

Figure 7-2 S720 label example



The picture above is only for reference.

## 7.3 Packaging

The S720 module uses a surface-mount method for furnace welding. A moisture-proof packaging method is used to prevent the product from being moist from production to users' use. That is, a processing method, such as using the aluminum foil bag, desiccant, humidity indicator card, tray, or vacuum, is used to ensure the dryness of the product and prolong the lifetime.

### 7.3.1 Tray

The mass-produced S720 will be packaged and delivered in the following manner:

Figure 7-3 Tray package

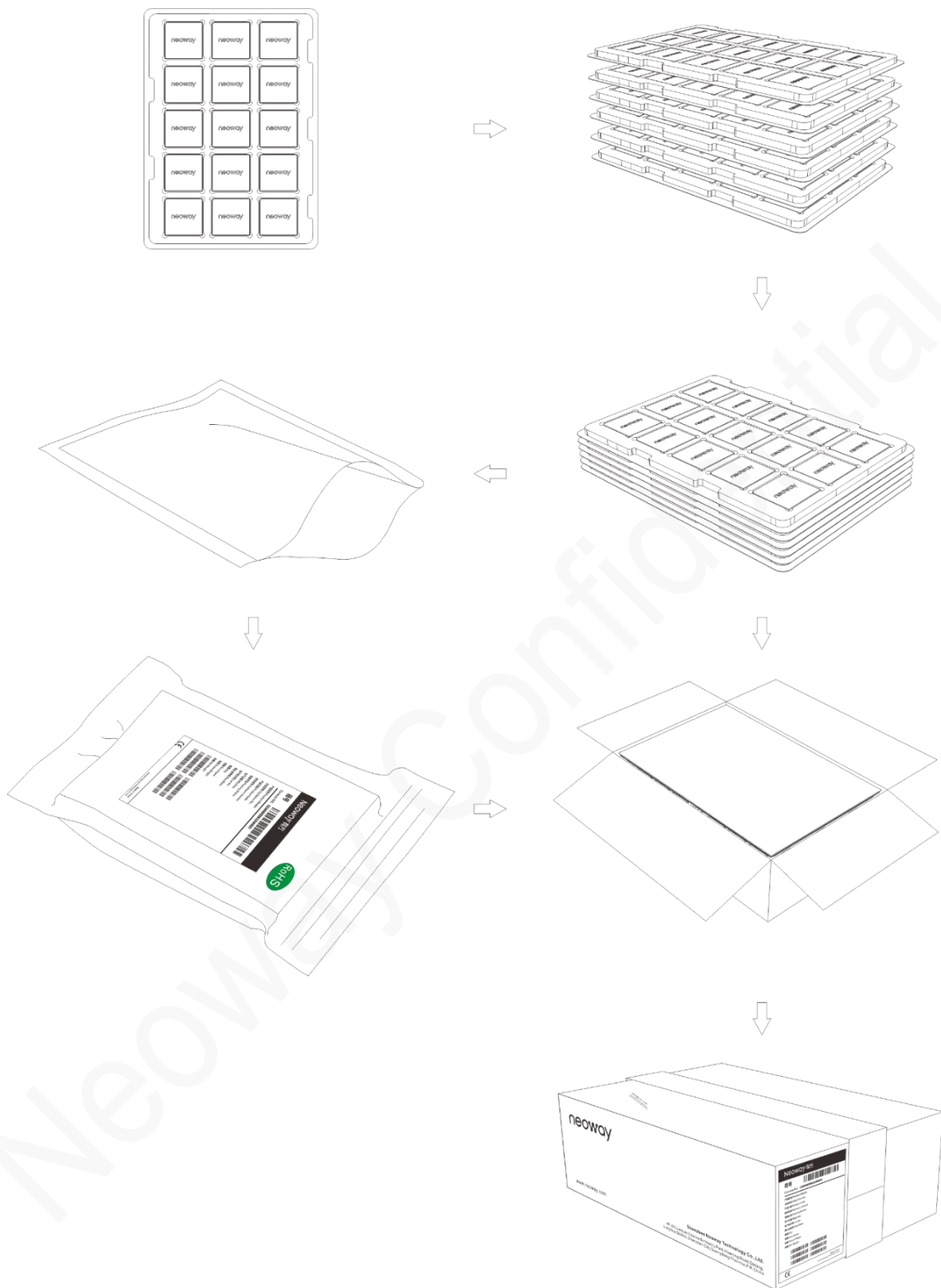
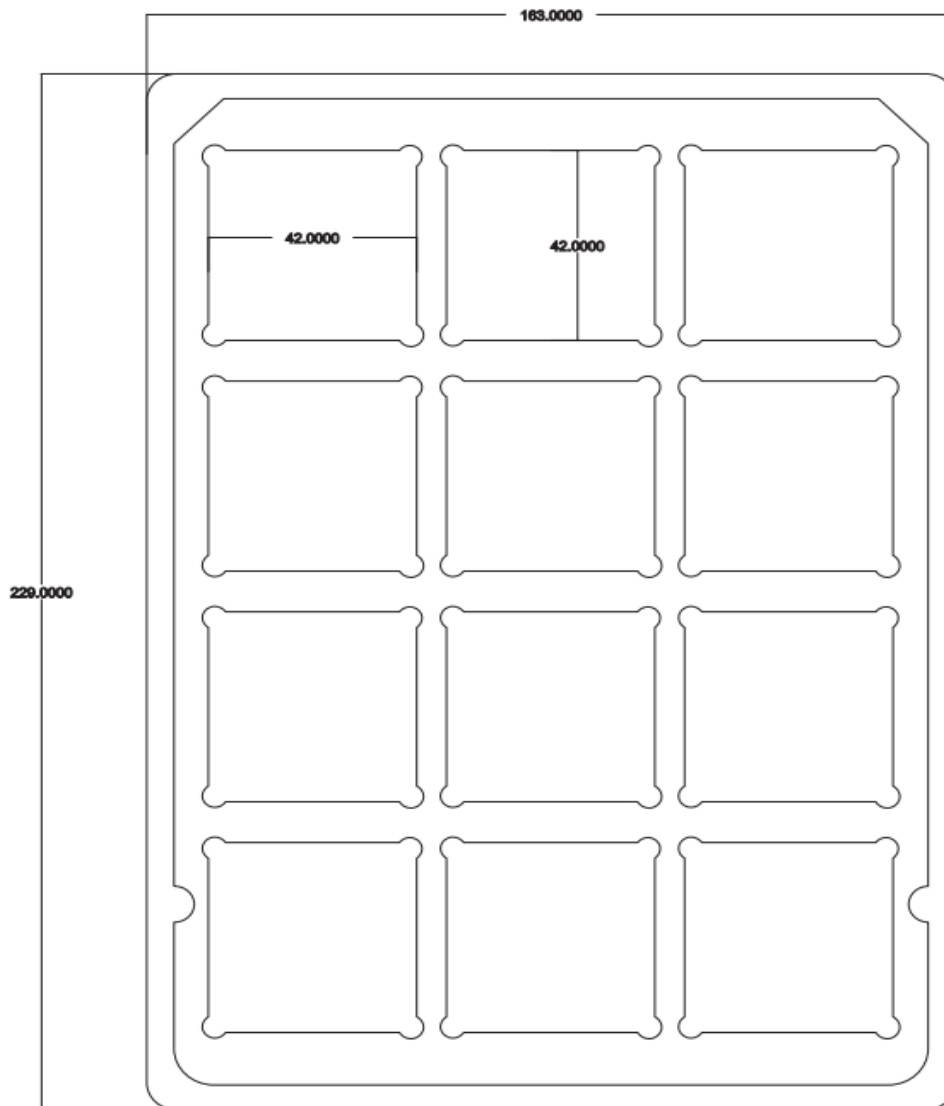


Figure 7-4 Tray



### 7.3.2 Moisture

S720 is a level-3 moisture sensitive device, in compliance with standard IPC/JEDEC J-STD-020. Pay attention to all the related requirements for using this kind of components.

After the module is unpacked, if it is exposed to the air for a long time, the module will be moist, and the module may be damaged during reflow soldering or welding in a lab. It is recommended that the module exposed to the air for a long time should be baked before it can be used again. The baking conditions are determined based on the moisture condition. It is recommended to bake the module at a temperature higher than 90 degrees for more than 12 hours. In addition, since the tray is of non-high temperature resistant material, the module cannot be baked directly on the plastic tray.

## 7.4 Storage

- Storage temperature range: 20°C to 26°C
- Storage humidity: 40% to 60%
- Storage period: 120 days

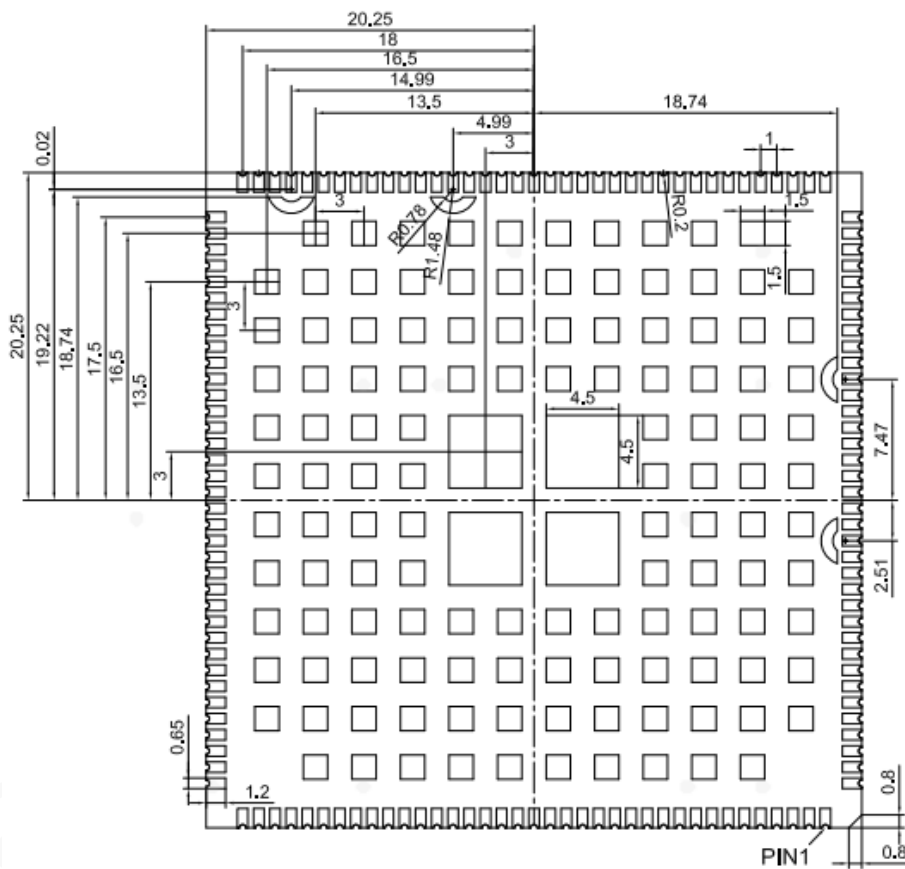
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## 8 Assembly

The S720 module is assembled by using 146-pin LCC+128-pin LGA and SMD welding.

### 8.1 Module PCB Package

Figure 8-1 Bottom view of the S720 module PCB package (unit: mm)





- The melting temperature of solder pastes with lead is 35°C lower than that of solder pastes without lead. The temperature in the reflow process parameters is also lower than that of solder pastes without lead, and less time is consumed correspondingly. It is easy to cause the LCC/LGA in the module to be in the semi-melted state after the second reflow soldering, resulting in poor soldering.
- If users must use solder pastes with lead, ensure that the reflow temperature is kept at 220°C for more than 45 seconds and the peak temperature reaches 240°C.

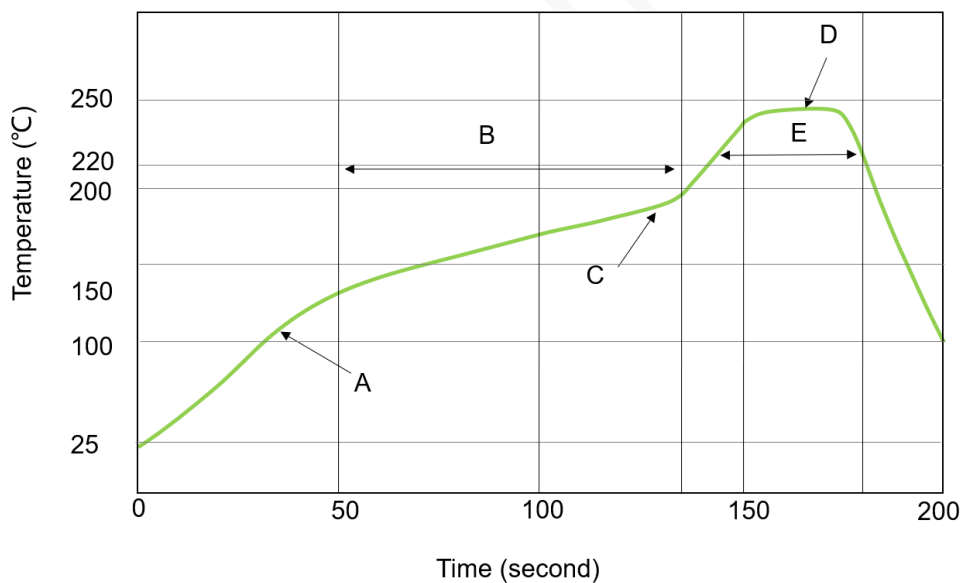
## 8.4 SMT Furnace Temperature Curve



Neoway will not provide a warranty for thermal component exceptions caused by improper temperature control.

Thin or long PCB might bend during SMT. Therefore, use loading tools during the SMT and reflow soldering process to avoid poor solder joint caused by PCB bending.

Figure 8-3 SMT furnace temperature curve



Technical parameters:

- Ramp-up rate: 1°C/sec to 4°C/sec
- Ramp-down rate: -3°C/sec to -1°C/sec
- Soaking zone: 150–180°C, time: 60–100s
- Reflow zone: > 220°C, time: 40–90s
- Peak temperature: 235–245°C

For information about important notes in S720 storage and mounting, refer to *Neoway\_Reflow\_Soldering\_Guidelines\_For\_Surface-Mounted\_Modules*.

When manually desoldering the module, use heat guns with great opening, adjust the temperature to about 245°C (depending on the type of the solder paste), and heat the module till the solder paste is melt. Then gently remove the module using tweezers. Do not shake the module in high temperatures while removing it. Otherwise, the components inside the module might get misplaced and cannot be repaired.

## A Abbreviations

| Abbreviation | Full Name                               |
|--------------|---|
| AAC          | Advanced Audio Coding                   |
| ADC          | Analog-Digital Converter                |
| AMR          | Adaptive Multi-Rate                     |
| ANT          | Antenna                                 |
| AP           | Access Point                            |
| ARM          | Advanced RISC Machine                   |
| BDS          | BeiDou Navigation Satellite System      |
| BLE          | Bluetooth Low Energy                    |
| BT           | Bluetooth                               |
| CNR          | Carrier to Noise Rate                   |
| DCS          | Digital Cellular System                 |
| DL           | Downlink                                |
| DSI          | Display Serial Interface                |
| EDGE         | Enhanced Data Rate for GSM Evolution    |
| EGSM         | Enhanced GSM                            |
| ESD          | Electronic Static Discharge             |
| FDD          | Frequency Division Duplexing            |
| GLONASS      | GLOBAL NAVIGATION SATELLITE SYSTEM      |
| GND          | Ground                                  |
| GNSS         | Global Navigation Satellite System      |
| GPIO         | General Purpose Input Output            |
| GPRS         | General Packet Radio Service            |
| GPS          | Global Positioning System               |
| GSM          | Global System for Mobile Communications |
| HSDPA        | High Speed Downlink Packet Access       |
| I2C          | Inter-Integrated Circuit                |
| LCC          | Leadless Chip Carriers                  |

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|       |  |
|-------|--|
| LCD   | Liquid Crystal Display                       |
| LGA   | Land Grid Array                              |
| LPDDR | Low Power Double Data Rate                   |
| LTE   | Long Term Evolution                          |
| MIC   | Microphone                                   |
| MIPI  | Mobile Industry Processor Interface          |
| MP3   | Moving Picture Experts Group Audio Layer III |
| PCB   | Printed Circuit Board                        |
| PCS   | Personal Communications Service              |
| PWM   | Pulse Width Modulation                       |
| QVGA  | Quarter Video Graphics Array                 |
| QZSS  | Quasi-Zenith Satellite System                |
| RF    | Radio Frequency                              |
| SD    | Secure Digital                               |
| SDIO  | Secure Digital Input Output                  |
| SIM   | Subscriber Identification Module             |
| SPI   | Serial Peripheral Interface                  |
| TDD   | Time Division Duplex                         |
| UART  | Universal Asynchronous Receiver-Transmitter  |
| UL    | Uplink                                       |
| USB   | Universal Serial Bus                         |
| USIM  | Universal Subscriber Identity Module         |
| VBAT  | Battery Voltage                              |
| WCDMA | Wideband Code Division Multiple Access       |
| Wi-Fi | Wireless Fidelity                            |
| WLAN  | Wireless Local Area Network                  |
| WVGA  | Wide Video Graphics Array                    |

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